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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I ² C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	A/D 5x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc72-04i-so

PIC16C72 Series

TABLE 1-1 PIC16C72/CR72 PINOUT DESCRIPTION

Pin Name	Pin#	I/O/P Type	Buffer Type	Description
OSC1/CLKIN	9	I	ST/CMOS ⁽³⁾	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	10	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal oscillator mode. In RC mode, the OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
MCLR/VPP	1	I/P	ST	Master clear (reset) input or programming voltage input. This pin is an active low reset to the device.
RA0/AN0	2	I/O	TTL	PORTA is a bi-directional I/O port. RA0 can also be analog input0. RA1 can also be analog input1. RA2 can also be analog input2. RA3 can also be analog input3 or analog reference voltage RA4 can also be the clock input to the Timer0 module. Output is open drain type. RA5 can also be analog input4 or the slave select for the synchronous serial port.
RA1/AN1	3	I/O	TTL	
RA2/AN2	4	I/O	TTL	
RA3/AN3/VREF	5	I/O	TTL	
RA4/T0CKI	6	I/O	ST	
RA5/SS/AN4	7	I/O	TTL	
RB0/INT	21	I/O	TTL/ST ⁽¹⁾	PORTB is a bi-directional I/O port. PORTB can be software programmed for internal weak pull-up on all inputs. RB0 can also be the external interrupt pin. Interrupt on change pin. Interrupt on change pin. Interrupt on change pin. Serial programming clock. Interrupt on change pin. Serial programming data.
RB1	22	I/O	TTL	
RB2	23	I/O	TTL	
RB3	24	I/O	TTL	
RB4	25	I/O	TTL	
RB5	26	I/O	TTL	
RB6	27	I/O	TTL/ST ⁽²⁾	
RB7	28	I/O	TTL/ST ⁽²⁾	
RC0/T1OSO/T1CKI	11	I/O	ST	PORTC is a bi-directional I/O port. RC0 can also be the Timer1 oscillator output or Timer1 clock input. RC1 can also be the Timer1 oscillator input. RC2 can also be the Capture1 input/Compare1 output/PWM1 output. RC3 can also be the synchronous serial clock input/output for both SPI and I ² C modes. RC4 can also be the SPI Data In (SPI mode) or data I/O (I ² C mode). RC5 can also be the SPI Data Out (SPI mode).
RC1/T1OSI	12	I/O	ST	
RC2/CCP1	13	I/O	ST	
RC3/SCK/SCL	14	I/O	ST	
RC4/SDI/SDA	15	I/O	ST	
RC5/SDO	16	I/O	ST	
RC6	17	I/O	ST	
RC7	18	I/O	ST	
Vss	8, 19	P	—	Ground reference for logic and I/O pins.
VDD	20	P	—	Positive supply for logic and I/O pins.

Legend: I = input O = output I/O = input/output P = power
 — = Not used TTL = TTL input ST = Schmitt Trigger input

- Note 1:** This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in serial programming mode.
3: This buffer is a Schmitt Trigger input when configured in RC oscillator mode and a CMOS input otherwise.

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2.2.2.4 PIE1 REGISTER

This register contains the individual enable bits for the peripheral interrupts.

Note: Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

FIGURE 2-6: PIE1 REGISTER (ADDRESS 8Ch)

U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	ADIE	—	—	SSPIE	CCP1IE	TMR2IE	TMR1IE
bit7				bit0			

R = Readable bit
W = Writable bit
U = Unimplemented bit,
read as '0'
- n = Value at POR reset

bit 7: **Unimplemented:** Read as '0'

bit 6: **ADIE:** A/D Converter Interrupt Enable bit
1 = Enables the A/D interrupt
0 = Disables the A/D interrupt

bit 5-4: **Unimplemented:** Read as '0'

bit 3: **SSPIE:** Synchronous Serial Port Interrupt Enable bit
1 = Enables the SSP interrupt
0 = Disables the SSP interrupt

bit 2: **CCP1IE:** CCP1 Interrupt Enable bit
1 = Enables the CCP1 interrupt
0 = Disables the CCP1 interrupt

bit 1: **TMR2IE:** TMR2 to PR2 Match Interrupt Enable bit
1 = Enables the TMR2 to PR2 match interrupt
0 = Disables the TMR2 to PR2 match interrupt

bit 0: **TMR1IE:** TMR1 Overflow Interrupt Enable bit
1 = Enables the TMR1 overflow interrupt
0 = Disables the TMR1 overflow interrupt

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TABLE 3-5 PORTC FUNCTIONS

Name	Bit#	Buffer Type	Function
RC0/T1OSO/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator output/Timer1 clock input
RC1/T1OSI	bit1	ST	Input/output port pin or Timer1 oscillator input
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I ² C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I ² C mode).
RC5/SDO	bit5	ST	Input/output port pin or Synchronous Serial Port data output
RC6	bit6	ST	Input/output port pin
RC7	bit7	ST	Input/output port pin

Legend: ST = Schmitt Trigger input

TABLE 3-6 SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
07h	PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	uuuu uuuu
87h	TRISC	PORTC Data Direction Register								1111 1111	1111 1111

Legend: x = unknown, u = unchanged.

5.2 Timer1 Oscillator

A crystal oscillator circuit is built in between pins T1OSI (input) and T1OSO (amplifier output). It is enabled by setting control bit T1OSCEN (T1CON<3>). The oscillator is a low power oscillator rated up to 200 kHz. It will continue to run during SLEEP. It is primarily intended for a 32 kHz crystal. Table 5-1 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is identical to the LP oscillator. The user must provide a software time delay to ensure proper oscillator start-up.

TABLE 5-1 CAPACITOR SELECTION FOR THE TIMER1 OSCILLATOR

Osc Type	Freq	C1	C2
LP	32 kHz	33 pF	33 pF
	100 kHz	15 pF	15 pF
	200 kHz	15 pF	15 pF
These values are for design guidance only.			
Crystals Tested:			
32.768 kHz	Epson C-001R32.768K-A	± 20 PPM	
100 kHz	Epson C-2 100.00 KC-P	± 20 PPM	
200 kHz	STD XTL 200.000 kHz	± 20 PPM	
Note 1: Higher capacitance increases the stability of oscillator but also increases the start-up time.			
2: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.			

5.3 Timer1 Interrupt

The TMR1 Register pair (TMR1H:TMR1L) increments from 0000h to FFFFh and rolls over to 0000h. The TMR1 Interrupt, if enabled, is generated on overflow which is latched in interrupt flag bit TMR1IF (PIR1<0>). This interrupt can be enabled/disabled by setting/clearing TMR1 interrupt enable bit TMR1IE (PIE1<0>).

5.4 Resetting Timer1 using a CCP Trigger Output

If the CCP module is configured in compare mode to generate a "special event trigger" (CCP1M3:CCP1M0 = 1011), this signal will reset Timer1 and start an A/D conversion (if the A/D module is enabled).

Note: The special event triggers from the CCP1 module will not set interrupt flag bit TMR1IF (PIR1<0>).

Timer1 must be configured for either timer or synchronized counter mode to take advantage of this feature. If Timer1 is running in asynchronous counter mode, this reset operation may not work.

In the event that a write to Timer1 coincides with a special event trigger from CCP1, the write will take precedence.

In this mode of operation, the CCPR1H:CCPR1L registers pair effectively becomes the period register for Timer1.

TABLE 5-2 REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
0Bh,8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	(1)	ADIF	(1)	(1)	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
8Ch	PIE1	(1)	ADIE	(1)	(1)	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
0Eh	TMR1L	Holding register for the Least Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
0Fh	TMR1H	Holding register for the Most Significant Byte of the 16-bit TMR1 register								xxxx xxxx	uuuu uuuu
10h	T1CON	—	—	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR1ON	--00 0000	--uu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by the Timer1 module.

Note 1: These bits are unimplemented, read as '0'.

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8.4.1.1 ADDRESSING

Once the SSP module has been enabled, it waits for a START condition to occur. Following the START condition, the 8-bits are shifted into the SSPSR register. All incoming bits are sampled with the rising edge of the clock (SCL) line. The value of register SSPSR<7:1> is compared to the value of the SSPADD register. The address is compared on the falling edge of the eighth clock (SCL) pulse. If the addresses match, and the BF and SSPOV bits are clear, the following events occur:

- The SSPSR register value is loaded into the SSPBUF register.
- The buffer full bit, BF is set.
- An $\overline{\text{ACK}}$ pulse is generated.
- SSP interrupt flag bit, SSPIF (PIR1<3>) is set (interrupt is generated if enabled) - on the falling edge of the ninth SCL pulse.

In 10-bit address mode, two address bytes need to be received by the slave. The five Most Significant bits (MSbs) of the first address byte specify if this is a 10-bit address. Bit $\text{R}/\overline{\text{W}}$ (SSPSTAT<2>) must specify a write so the slave device will receive the second address byte. For a 10-bit address the first byte would equal

'1111 0 A9 A8 0', where A9 and A8 are the two MSbs of the address. The sequence of events for 10-bit address is as follows, with steps 7- 9 for slave-transmitter:

- Receive first (high) byte of Address (bits SSPIF, BF, and bit UA (SSPSTAT<1>) are set).
- Update the SSPADD register with second (low) byte of Address (clears bit UA and releases the SCL line).
- Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.
- Receive second (low) byte of Address (bits SSPIF, BF, and UA are set).
- Update the SSPADD register with the first (high) byte of Address, if match releases SCL line, this will clear bit UA.
- Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.
- Receive repeated START condition.
- Receive first (high) byte of Address (bits SSPIF and BF are set).
- Read the SSPBUF register (clears bit BF) and clear flag bit SSPIF.

TABLE 8-3 DATA TRANSFER RECEIVED BYTE ACTIONS

Status Bits as Data Transfer is Received		SSPSR → SSPBUF	Generate $\overline{\text{ACK}}$ Pulse	Set bit SSPIF (SSP Interrupt occurs if enabled)
BF	SSPOV			
0	0	Yes	Yes	Yes
1	0	No	No	Yes
1	1	No	No	Yes
0	1	No	No	Yes

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NOTES:

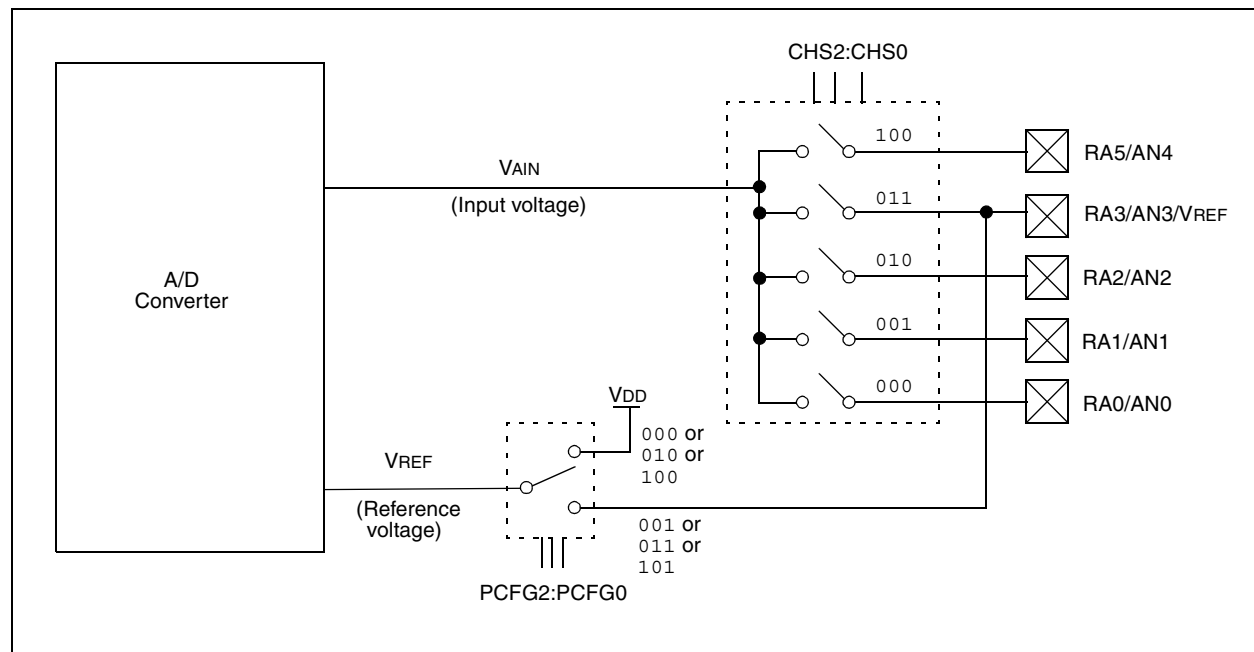
The ADRES register contains the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRES register, the GO/DONE bit (ADCON0<2>) is cleared, and A/D interrupt flag bit ADIF is set. The block diagram of the A/D module is shown in Figure 9-3.

The value that is in the ADRES register is not modified for a Power-on Reset. The ADRES register will contain unknown data after a Power-on Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see Section 9.1. After this acquisition time has elapsed the A/D conversion can be started. The following steps should be followed for doing an A/D conversion:

1. Configure the A/D module:
 - Configure analog pins / voltage reference / and digital I/O (ADCON1)
 - Select A/D input channel (ADCON0)
 - Select A/D conversion clock (ADCON0)
 - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
 - Clear ADIF bit
 - Set ADIE bit
 - Set GIE bit
3. Wait the required acquisition time.
4. Start conversion:
 - Set GO/DONE bit (ADCON0)
5. Wait for A/D conversion to complete, by either:
 - Polling for the GO/DONE bit to be cleared
 OR
 - Waiting for the A/D interrupt
6. Read A/D Result register (ADRES), clear bit ADIF if required.
7. For next conversion, go to step 1 or step 2 as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2TAD is required before next acquisition starts.

FIGURE 9-3: A/D BLOCK DIAGRAM



9.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 9.5TAD per 8-bit conversion. The source of the A/D conversion clock is software selectable. The four possible options for TAD are:

- 2TOSC
- 8TOSC
- 32TOSC
- Internal RC oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 μ s.

Table 9-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

9.3 Configuring Analog Port Pins

The ADCON1, TRISA, and TRISE registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS2:CHS0 bits and the TRIS bits.

Note 1: When reading the port register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs, will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.

Note 2: Analog levels on any pin that is defined as a digital input (including the AN4:AN0 pins), may cause the input buffer to consume current that is out of the devices specification.

TABLE 9-1 TAD vs. DEVICE OPERATING FREQUENCIES

AD Clock Source (TAD)		Device Frequency			
Operation	ADCS1:ADCS0	20 MHz	5 MHz	1.25 MHz	333.33 kHz
2TOSC	00	100 ns ⁽²⁾	400 ns ⁽²⁾	1.6 μ s	6 μ s
8TOSC	01	400 ns ⁽²⁾	1.6 μ s	6.4 μ s	24 μ s ⁽³⁾
32TOSC	10	1.6 μ s	6.4 μ s	25.6 μ s ⁽³⁾	96 μ s ⁽³⁾
RC ⁽⁵⁾	11	2 - 6 μ s ^(1,4)	2 - 6 μ s ^(1,4)	2 - 6 μ s ^(1,4)	2 - 6 μ s ⁽¹⁾

Legend: Shaded cells are outside of recommended range.

Note 1: The RC source has a typical TAD time of 4 μ s.

2: These values violate the minimum required TAD time.

3: For faster conversion times, the selection of another clock source is recommended.

4: When device frequency is greater than 1 MHz, the RC A/D conversion clock source is recommended for sleep operation only.

5: For extended voltage devices (LC), please refer to Electrical Specifications section.

TABLE 10-6 INITIALIZATION CONDITIONS FOR ALL REGISTERS

Register	Power-on Reset, Brown-out Reset	MCLR Resets WDT Reset	Wake-up via WDT or Inter- rupt
W	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	N/A	N/A	N/A
TMR0	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000h	0000h	PC + 1 ⁽²⁾
STATUS	0001 1xxx	000q quuu ⁽³⁾	uuuq quuu ⁽³⁾
FSR	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	--0x 0000	--0u 0000	--uu uuuu
PORTB	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTC	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCLATH	---0 0000	---0 0000	---u uuuu
INTCON	0000 000x	0000 000u	uuuu uuuu ⁽¹⁾
PIR1	-0-- 0000	-0-- 0000	-u-- uuuu ⁽¹⁾
TMR1L	xxxx xxxx	uuuu uuuu	uuuu uuuu
TMR1H	xxxx xxxx	uuuu uuuu	uuuu uuuu
T1CON	--00 0000	--uu uuuu	--uu uuuu
TMR2	0000 0000	0000 0000	uuuu uuuu
T2CON	-000 0000	-000 0000	-uuu uuuu
SSPBUF	xxxx xxxx	uuuu uuuu	uuuu uuuu
SSPCON	0000 0000	0000 0000	uuuu uuuu
CCPR1L	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR1H	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP1CON	--00 0000	--00 0000	--uu uuuu
ADRES	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	0000 00-0	0000 00-0	uuuu uu-u
OPTION	1111 1111	1111 1111	uuuu uuuu
TRISA	--11 1111	--11 1111	--uu uuuu
TRISB	1111 1111	1111 1111	uuuu uuuu
TRISC	1111 1111	1111 1111	uuuu uuuu
PIE1	-0-- 0000	-0-- 0000	-u-- uuuu
PCON	---- --0u	---- --uu	---- --uu
PR2	1111 1111	1111 1111	1111 1111
SSPADD	0000 0000	0000 0000	uuuu uuuu
SSPSTAT	--00 0000	--00 0000	--uu uuuu
ADCON1	---- -000	---- -000	---- -uuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition

Note 1: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: See Table 10-5 for reset value for specific condition.

10.11 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt, i.e., W register and STATUS register. This will have to be implemented in software.

Example 10-1 stores and restores the W and STATUS registers. The register, W_TEMP, must be defined in each bank and must be defined at the same offset from the bank base address (i.e., if W_TEMP is defined at 0x20 in bank 0, it must also be defined at 0xA0 in bank 1).

The example:

- a) Stores the W register.
- b) Stores the STATUS register in bank 0.
- c) Executes the ISR code.
- d) Restores the STATUS register (and bank select bit).
- e) Restores the W register.

EXAMPLE 10-1: SAVING STATUS, W, AND PCLATH REGISTERS IN RAM

```
MOVWF    W_TEMP          ;Copy W to W_TEMP register, could be bank one or zero
SWAPF    STATUS,W         ;Swap status to be saved into W
CLRF     STATUS           ;bank 0, regardless of current bank, Clears IRP,RP1,RP0
MOVWF    STATUS_TEMP      ;Save status to bank zero STATUS_TEMP register
:
: Interrupt Service Routine (ISR) - user defined
:
SWAPF    STATUS_TEMP,W    ;Swap STATUS_TEMP register into W
                        ; (sets bank to original state)
MOVWF    STATUS           ;Move W into STATUS register
SWAPF    W_TEMP,F         ;Swap W_TEMP
SWAPF    W_TEMP,W         ;Swap W_TEMP into W
```

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TABLE 11-2 PIC16CXXX INSTRUCTION SET

Mnemonic, Operands	Description	Cycles	14-Bit Opcode				Status Affected	Notes	
			MSb		LSb				
BYTE-ORIENTED FILE REGISTER OPERATIONS									
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	f	Clear f	1	00	0001	1fff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0xxx	xxxx	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1,2,3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	1fff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	C	1,2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	C	1,2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIENTED FILE REGISTER OPERATIONS									
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
LITERAL AND CONTROL OPERATIONS									
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	$\overline{TO}, \overline{PD}$	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into standby mode	1	00	0000	0110	0011	$\overline{TO}, \overline{PD}$	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

Note 1: When an I/O register is modified as a function of itself (e.g., `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.

3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

13.0 ELECTRICAL CHARACTERISTICS - PIC16C72 SERIES

Absolute Maximum Ratings †

Parameter	PIC16C72	PIC16CR72
Ambient temperature under bias	-55 to +125°C	-55 to +125°C
Storage temperature	-65°C to +150°C	-65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, $\overline{\text{MCLR}}$, and RA4)	-0.3V to (VDD + 0.3V)	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS	-0.3 to +7.5V	TBD
Voltage on $\overline{\text{MCLR}}$ with respect to VSS (Note 1)	-0.3 to +14V	TBD
Voltage on RA4 with respect to VSS	-0.3 to +14V	TBD
Total power dissipation (Note 2)	1.0W	1.0W
Maximum current out of VSS pin	300 mA	300 mA
Maximum current into VDD pin	250 mA	250 mA
Input clamp current, I _{IK} (V _I < 0 or V _I > VDD)	± 20 mA	± 20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > VDD)	± 20 mA	± 20 mA
Maximum output current sunk by any I/O pin	25 mA	25 mA
Maximum output current sourced by any I/O pin	25 mA	25 mA
Maximum current sunk by PORTA and PORTB (combined)	200 mA	200 mA
Maximum current sourced by PORTA and PORTB (combined)	200 mA	200 mA
Maximum current sunk by PORTC	200 mA	200 mA
Maximum current sourced by PORTC	200 mA	200 mA
1. Voltage spikes below VSS at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the $\overline{\text{MCLR}}$ pin rather than pulling this pin directly to VSS. 2. Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$.		
† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.		

13.1 DC Characteristics: PIC16C72/CR72-04 (Commercial, Industrial, Extended) PIC16C72/CR72-10 (Commercial, Industrial, Extended) PIC16C72/CR72-20 (Commercial, Industrial, Extended)

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C for extended, -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial										
DC CHARACTERISTICS										
Param No.	Characteristic	Sym	PIC16C72			PIC16CR72			Units	Conditions
			Min	Typ†	Max	Min	Typ†	Max		
D001	Supply Voltage	VDD	4.0	-	6.0	4.0	-	5.5	V	XT, RC and LP osc
D001A			4.5	-	5.5	4.5	-	5.5	V	HS osc
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset Signal	VPOR	-	VSS	-	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset Signal	SVDD	0.05	-	-	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	Bvdd	3.7	4.0	4.3	3.7	4.0	4.3	V	BODEN bit in configuration word enabled
			3.7	4.0	4.4	3.7	4.0	4.4	V	Extended Only
D010	Supply Current (Note 2,5)	IDD	-	2.7	5.0	-	2.7	5.0	mA	XT, RC osc FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	10	20	-	10	20	mA	HS osc FOSC = 20 MHz, VDD = 5.5V
D015	Brown-out Reset Current (Note 6)	ΔIbor	-	350	425	-	350	425	μA	BOR enabled, VDD = 5.0V
D020	Power-down Current (Note 3,5)	IPD	-	10.5	42	-	10.5	42	μA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021			-	1.5	16	-	1.5	16	μA	VDD = 4.0V, WDT disabled, -0°C to +70°C
D021A			-	1.5	19	-	1.5	19	μA	VDD = 4.0V, WDT disabled, -40°C to +85°C
D021B			-	2.5	19	-	2.5	19	μA	VDD = 4.0V, WDT disabled, -40°C to +125°C
D023	Brown-out Reset Current (Note 6)	ΔIbor	-	350	425	-	350	425	μA	BOR enabled VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

Note 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

MCLR = VDD; WDT enabled/disabled as specified.

Note 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

Note 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula $I_r = VDD/2R_{ext}$ (mA) with Rext in kOhm.

Note 5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.

Note 6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

13.4 Timing Parameter Symbolology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS
3. TCC:ST (I²C specifications only)
4. Ts (I²C specifications only)

T		T	
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

pp		osc	OSC1
cc	CCP1	rd	\overline{RD}
ck	CLKOUT	rw	\overline{RD} or \overline{WR}
cs	\overline{CS}	sc	SCK
di	SDI	ss	\overline{SS}
do	SDO	t0	T0CKI
dt	Data in	t1	T1CKI
io	I/O port	wr	\overline{WR}
mc	\overline{MCLR}		

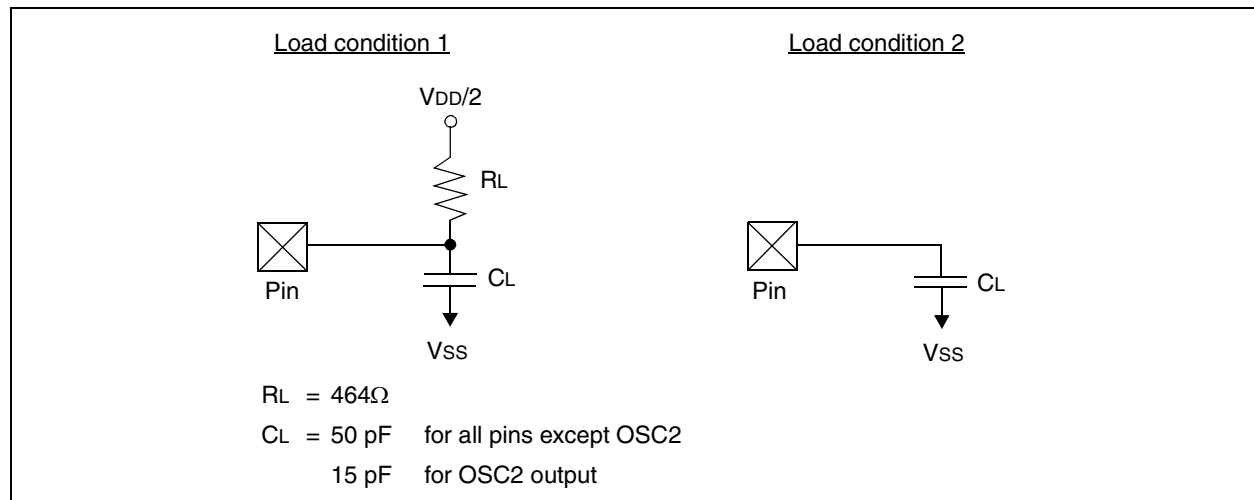
Uppercase letters and their meanings:

S		P	Period
F	Fall	R	Rise
H	High	V	Valid
I	Invalid (Hi-impedance)	Z	Hi-impedance
L	Low		
I ² C only		High	High
AA	output access	Low	Low
BUF	Bus free		

TCC:ST (I²C specifications only)

CC		SU	Setup
HD	Hold		
ST		STO	STOP condition
DAT	DATA input hold		
STA	START condition		

FIGURE 13-1: LOAD CONDITIONS



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FIGURE 13-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

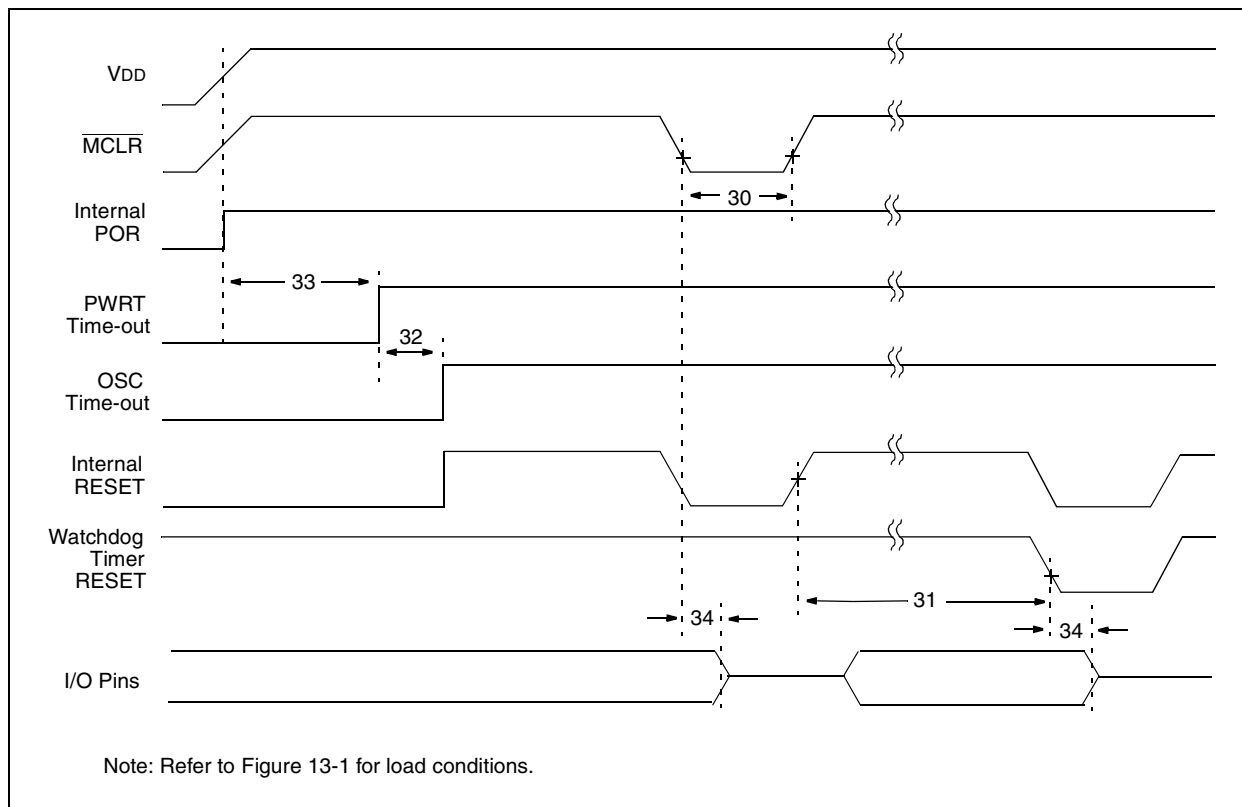


FIGURE 13-5: BROWN-OUT RESET TIMING

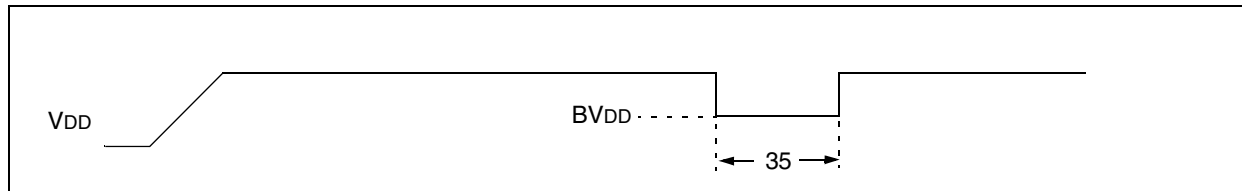


TABLE 13-5 RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmCL	MCLR Pulse Width (low)	2	—	—	μs	VDD = 5V, -40°C to +125°C
31*	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7	18	33	ms	VDD = 5V, -40°C to +125°C
32	Tost	Oscillation Start-up Timer Period	—	1024Tosc	—	—	Tosc = OSC1 period
33*	Tpwrt	Power-up Timer Period	28	72	132	ms	VDD = 5V, -40°C to +125°C
34	Tioz	I/O Hi-impedance from MCLR Low or Watchdog Timer Reset	—	—	2.1	μs	
35	TBOR	Brown-out Reset pulse width	100	—	—	μs	VDD ≤ BVDD (D005)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 13-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1)

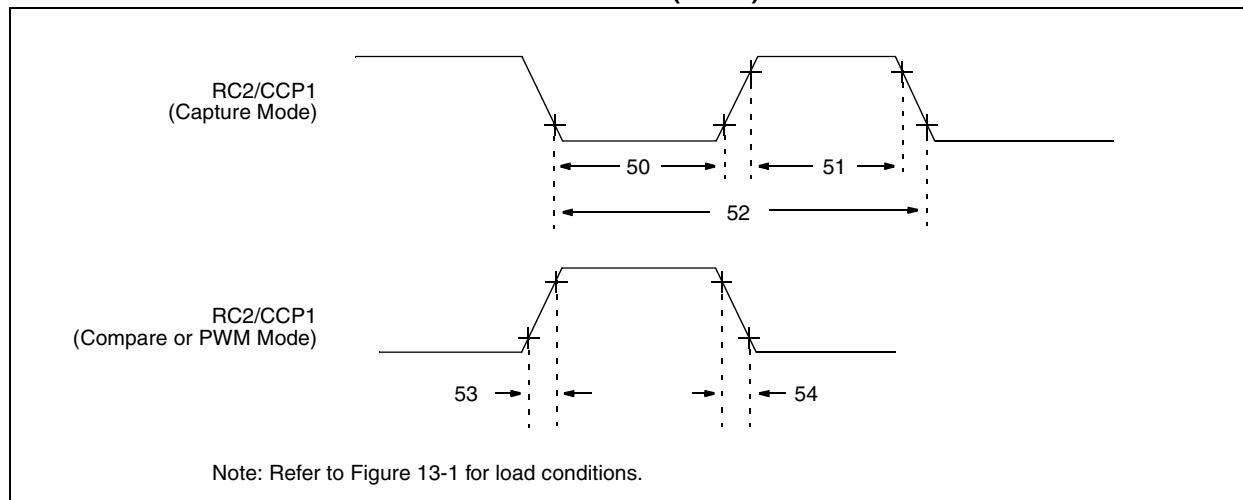


TABLE 13-7 CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1)

Param No.	Sym	Characteristic			Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 input low time	No Prescaler		$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16C72/CR72	10	—	—	ns	
				PIC16LC72/LCR72	20	—	—	ns	
51*	TccH	CCP1 input high time	No Prescaler		$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16C72/CR72	10	—	—	ns	
				PIC16LC72/LCR72	20	—	—	ns	
52*	TccP	CCP1 input period			$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1,4 or 16)
53*	TccR	CCP1 output rise time	PIC16C72/CR72		—	10	25	ns	
			PIC16LC72/LCR72		—	25	45	ns	
54*	TccF	CCP1 output fall time	PIC16C72/CR72		—	10	25	ns	
			PIC16LC72/LCR72		—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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TABLE 13-12 A/D CONVERTER CHARACTERISTICS:
PIC16C72/CR72-04 (Commercial, Industrial, Extended)
PIC16C72/CR72-10 (Commercial, Industrial, Extended)
PIC16C72/CR72-20 (Commercial, Industrial, Extended)
PIC16LC72/LCR72-04 (Commercial, Industrial)

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
A01	NR	Resolution	—	—	8 bits	bit	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A02	EABS	Total Absolute error	—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A03	EIL	Integral linearity error	—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A04	EDL	Differential linearity error	—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A05	EFS	Full scale error	—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A06	EOFF	Offset error	—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A10	—	Monotonicity	—	guaranteed	—	—	VSS ≤ VAIN ≤ VREF
A20	VREF	Reference voltage	2.5V	—	VDD + 0.3	V	
A25	VAIN	Analog input voltage	VSS - 0.3	—	VREF + 0.3	V	
A30	ZAIN	Recommended impedance of analog voltage source	—	—	10.0	kΩ	
A40	IAD	A/D conversion current (VDD)	PIC16C72/CR72	—	180	—	Average current consumption when A/D is on. (Note 1)
			PIC16LC72/LCR72	—	90	—	
A50	IREF	VREF input current (Note 2)	10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 9.1.
			—	—	10	μA	During A/D Conversion cycle

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current. The power-down current spec includes any such leakage from the A/D module.

Note 2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

FIGURE 14-16: TYPICAL I_{DD} vs. FREQUENCY (RC MODE @ 300 pF, 25°C)

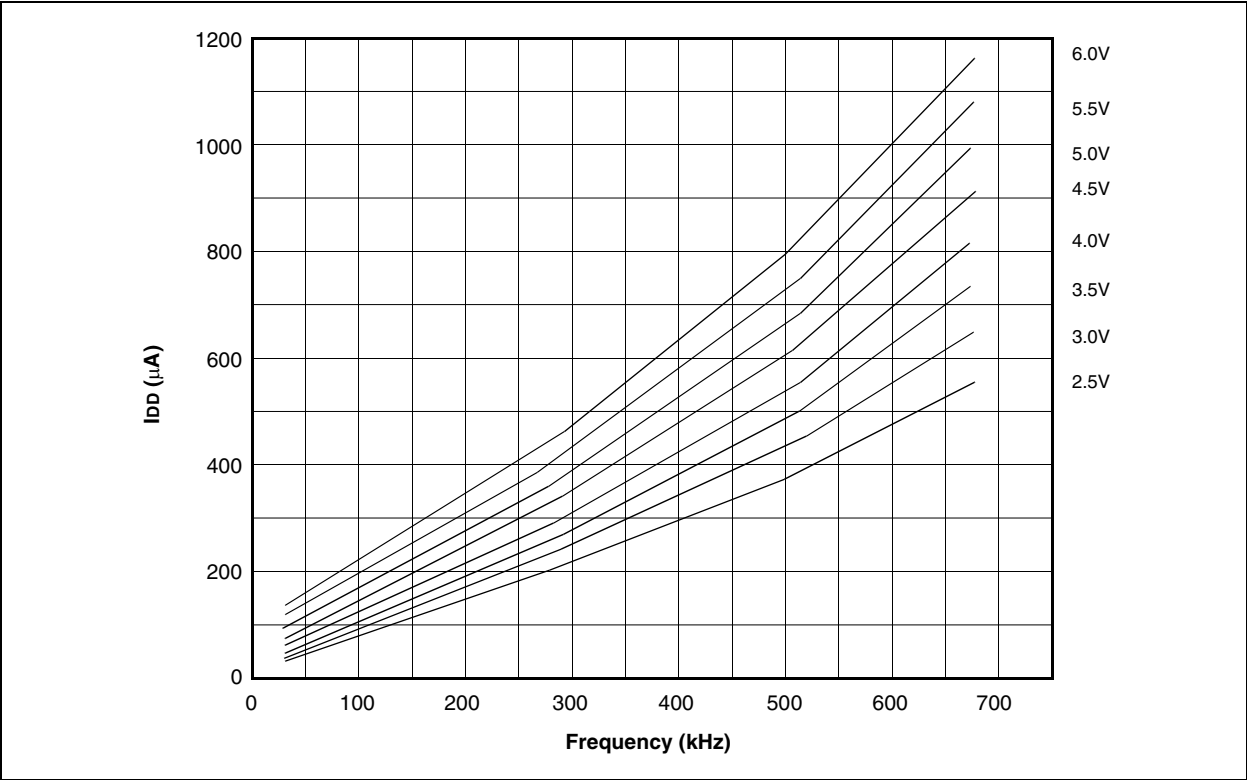
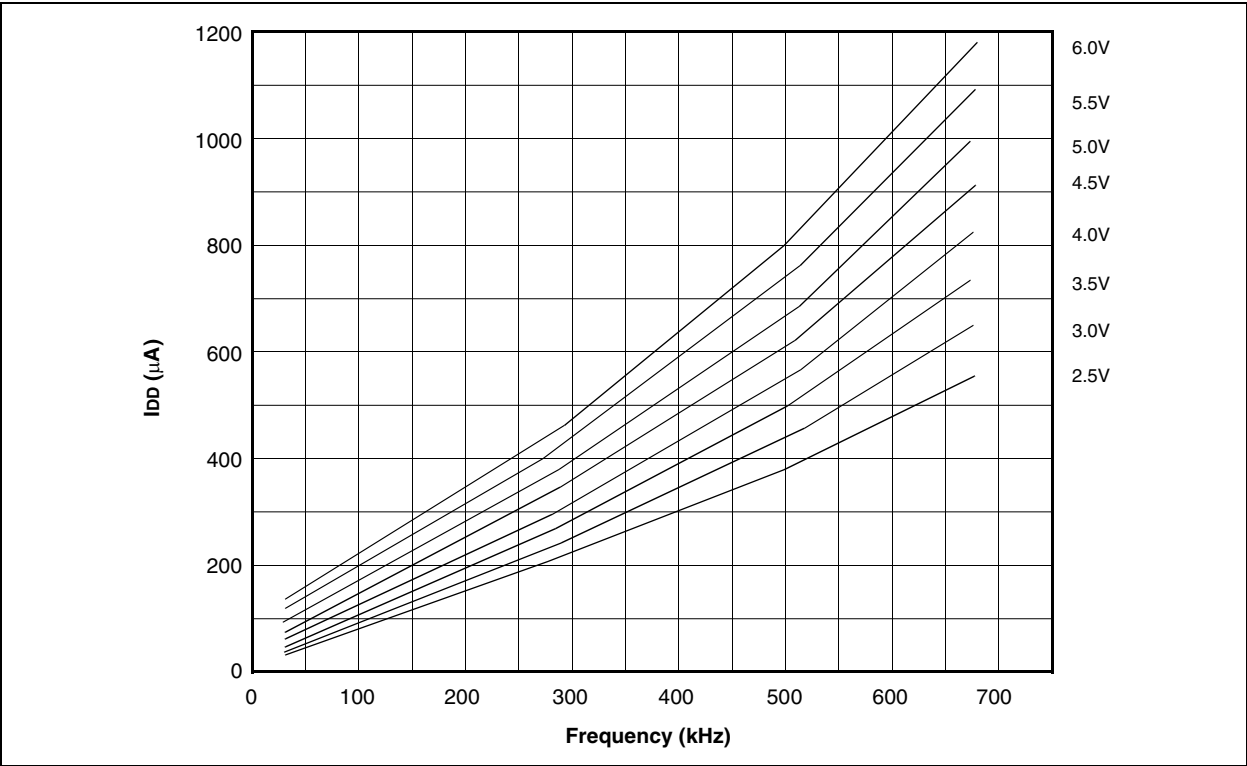


FIGURE 14-17: MAXIMUM I_{DD} vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)

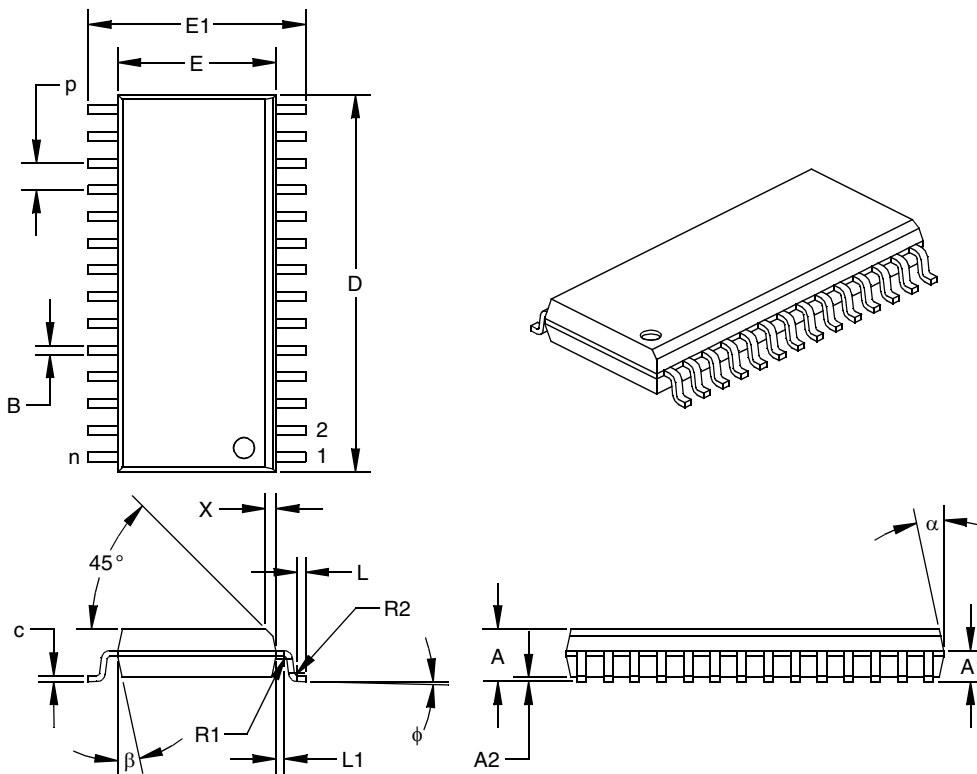


Data based on matrix samples. See first page of this section for details.

PIC16C72 Series

16.4 28-Lead Plastic Surface Mount (SOIC - Wide, 300 mil Body) (SO)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Pitch	p		0.050			1.27	
Number of Pins	n		28			28	
Overall Pack. Height	A	0.093	0.099	0.104	2.36	2.50	2.64
Shoulder Height	A1	0.048	0.058	0.068	1.22	1.47	1.73
Standoff	A2	0.004	0.008	0.011	0.10	0.19	0.28
Molded Package Length	D†	0.700	0.706	0.712	17.78	17.93	18.08
Molded Package Width	E‡	0.292	0.296	0.299	7.42	7.51	7.59
Outside Dimension	E1	0.394	0.407	0.419	10.01	10.33	10.64
Chamfer Distance	X	0.010	0.020	0.029	0.25	0.50	0.74
Shoulder Radius	R1	0.005	0.005	0.010	0.13	0.13	0.25
Gull Wing Radius	R2	0.005	0.005	0.010	0.13	0.13	0.25
Foot Length	L	0.011	0.016	0.021	0.28	0.41	0.53
Foot Angle	φ	0	4	8	0	4	8
Radius Centerline	L1	0.010	0.015	0.020	0.25	0.38	0.51
Lead Thickness	c	0.009	0.011	0.012	0.23	0.27	0.30
Lower Lead Width	B†	0.014	0.017	0.019	0.36	0.42	0.48
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter.

† Dimension "B" does not include dam-bar protrusions. Dam-bar protrusions shall not exceed 0.003" (0.076 mm) per side or 0.006" (0.152 mm) more than dimension "B."

‡ Dimensions "D" and "E" do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010" (0.254 mm) per side or 0.020" (0.508 mm) more than dimensions "D" or "E."

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